



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC057N08NS3 G	Issued	24. February 2022
MA#	MA005700297		
Package	PG-TDSON-8-1	Weight*	121.72 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.666	3.01	3.01	30120	30120
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	iron	7439-89-6	0.038	0.03		311	
	non noble metal	copper	7440-50-8	37.762	31.02	31.06	310230	310634
wire	non noble metal	copper	7440-50-8	0.068	0.06	0.06	555	555
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		667	
	plastics	epoxy resin	-	5.762	4.73		47339	
	inorganic material	silicondioxide	60676-86-0	34.735	28.54	33.34	285368	333374
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11926	11926
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1360	1360
solder	non noble metal	tin	7440-31-5	0.061	0.05		499	
	noble metal	silver	7440-22-4	0.076	0.06		624	
	non noble metal	lead	7439-92-1	2.899	2.38	2.49	23820	24943
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		183	
	noble metal	silver	7440-22-4	1.289	1.06		10593	
	non noble metal	copper	7440-50-8	22.292	18.31	19.40	183136	193967
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		93	
	non noble metal	copper	7440-50-8	11.320	9.30	9.31	93000	93121
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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